

## 6. PUBLICATION

1. Yang Kok Kee, Koay Hun Lee, Wan Jeffrey Basirun , Electrodeposition of tin using Tin (II) Methanesulfonate from mixture of Ionic Liquid and Methane Sulfonic Acid , *Advances In Materials And Processing Technologies (AMPT) 2009*.
2. Yang Kok Kee, Koay Hun Lee, Wan Jeffrey Basirun , Electrodeposition of tin using Tin (II) Methanesulfonate from mixture of Ionic Liquid and Methane Sulfonic Acid , *Patent Application, 2009, Status: Pending*
3. Yang Kok Kee, Koay Hun Lee, Wan Jeffrey Basirun , Voltammetry and Chronoamperometry of Tin (II) Methanesulfonate in Ionic Liquid and Methane Sulfonic Acid (MSA) solvent, *3<sup>rd</sup> International Conference on Functional Materials and Devices 2010 (ICFMD-2010)*.

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